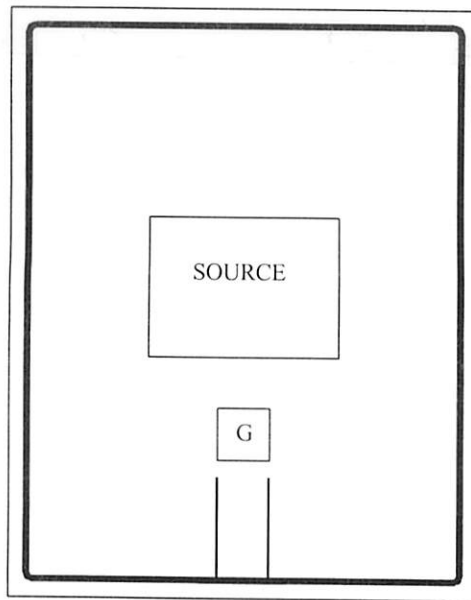




Sierra Components, Inc.

924 Incline Way • Suite F • Incline Village, Nevada 89451
Phone: 775.831.1241 Fax: 775.831.3021

Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.



HEX-4: 60V, N-CHANNEL

Topside Metal: Al
Backside: CrNiAg
Backside Potential:
Mask Ref: Gen 3
Bond Pads (Mils):

APPROVED BY:
MFG: Internat'l Rect

DIE SIZE (Mils): 170 x 240
THICKNESS:

DATE: 1/24/02
P/N: IRFC048

DG 10.1.2
Rev A 3-4-99